



Title of Change:	Final PCN for wafer fabrication site addition of ON Semiconductor Niigata Co., Ltd. (Group L)	
Proposed first ship date:	14 February 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <Osamu.Akaki@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>.	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Date code	
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Niigata, Japan	External Foundry/Subcon Sites: None
Description and Purpose:		
This is a Final Process Change Notification to announce the addition of a new wafer fabrication site for the device covered in this notice. Device formerly manufactured at the Manufacturers AMPI will be manufactured at ON Semiconductor Niigata Co., Ltd. (OSNC) following the expiration of this notice. OSNC located in Niigata, Japan has obtained ISO9001 certification. The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed to check the device functionality and electrical specifications.		



Reliability Data Summary:

QV DEVICE NAME FW389-TL-2W

RMS: 41557

PACKAGE: SOIC-8

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1,008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1,008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1,008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15,000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1,000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Autoclave	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Parts:

Part Number	Qualification Vehicle
FW389-TL-2W	FW389-TL-2W



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
FW389-TL-2W		FW389-TL-2W